

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
<b>CONVEYING PARTY DATA</b>													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Shai Haimson</td> <td>11/15/2010</td> </tr> <tr> <td>Avi Rozenblat</td> <td>11/15/2010</td> </tr> <tr> <td>Dror Horvitz</td> <td>11/15/2010</td> </tr> <tr> <td>Maor Rotlain</td> <td>11/15/2010</td> </tr> <tr> <td>Rotem Drori</td> <td>11/15/2010</td> </tr> </tbody> </table>		Name	Execution Date	Shai Haimson	11/15/2010	Avi Rozenblat	11/15/2010	Dror Horvitz	11/15/2010	Maor Rotlain	11/15/2010	Rotem Drori	11/15/2010
Name	Execution Date												
Shai Haimson	11/15/2010												
Avi Rozenblat	11/15/2010												
Dror Horvitz	11/15/2010												
Maor Rotlain	11/15/2010												
Rotem Drori	11/15/2010												
<b>RECEIVING PARTY DATA</b>													
Name:	Micron Technology, Inc.												
Street Address:	8000 South Federal Way												
City:	Boise												
State/Country:	IDAHO												
Postal Code:	83716-9632												
<b>PROPERTY NUMBERS Total: 1</b>													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12948897</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12948897								
Property Type	Number												
Application Number:	12948897												
<b>CORRESPONDENCE DATA</b>													
Fax Number:	(713)468-8883												
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
Phone:	713-468-8880												
Email:	trop@tphm.com												
Correspondent Name:	TROP, PRUNER & HU, P.C.												
Address Line 1:	1616 S. VOSS ROAD, SUITE 750												
Address Line 4:	HOUSTON, TEXAS 77057-2631												
ATTORNEY DOCKET NUMBER:	NUM.0236US												
NAME OF SUBMITTER:	Timothy N. Trop												

CH \$40.00 12948897

Total Attachments: 2

source=NUM0236\_Assignment#page1.tif

source=NUM0236\_Assignment#page2.tif

## ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

**Shai Haimson, Avi Rozenblat,  
Dror Horvitz, Maor Rotlain, and Rotem Drori**

hereby sell, assign, and transfer to:

**Micron Technology, Inc.**

a corporation of Delaware, having a principal place of business at 8000 South Federal Way, Boise, ID 83716-9632, United States of America ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and improvements that are disclosed in the application for the United States patent entitled:

### **Filling Cavities in Semiconductor Structures**

the Declaration for which has been executed by the undersigned prior hereto or concurrently herewith, said patent application which can also be identified as follows (if necessary):

**(I hereby authorize and request my attorney, associated with Customer Number 21906, to insert on the designated lines below, the filing date and application number of said application when known.)**

United States Patent Application Number \_\_\_\_\_ filed on \_\_\_\_\_.

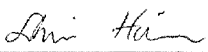
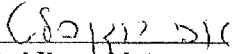



and in and to said application (nonprovisional or provisional) and all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all nonprovisional applications claiming priority to said application, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said inventions and improvements; and in and to all rights of priority resulting from the filing of said United States applications;

agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and

improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Each Inventor please sign and Date below

 _____ <b>Shai Haimson</b>	<u>15/11/2010</u> _____ (Today's Date)
 _____ <b>Avi Rozenblat</b>	<u>15/11/2010</u> _____ (Today's Date)
 _____ <b>Dror Horvitz</b>	<u>15/11/2010</u> _____ (Today's Date)
 _____ <b>Maor Rotlain</b>	<u>15/11/2010</u> _____ (Today's Date)
 _____ <b>Rotem Drori</b>	<u>15/11/10</u> _____ (Today's Date)